

Electronic Patent Application Fee Transmittal

Application Number:	10765931			
Filing Date:	29-Jan-2004			
Title of Invention:	Solder deposition method and solder bump forming method			
First Named Inventor/Applicant Name:	Youichi Kukimoto			
Filer:	Ken Sakurabayashi/Evette Ginn			
Attorney Docket Number:	Q79041			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$120 paid	1253	1	900	900

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				1690